

## Full Material Declaration for attached parts list

Report generated: 21 September 2016, 12:16 GMT



## Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2010 [Approved on 21 September 2016, 12:13 GMT]

## Materials and substances

| Use/Location  | Material group                                  | % w/w of material in the part | Substances in the material  | CAS Number | % w/w of substance in the material |
|---------------|-------------------------------------------------|-------------------------------|-----------------------------|------------|------------------------------------|
| Base material | Copper alloys                                   | 81.83000%                     | Copper                      | 7440-50-8  | 100.00000%                         |
| Chip (die)    | Other inorganic materials                       | 0.09000%                      | Silicon dioxide             | 60676-86-0 | 1.00000%                           |
|               |                                                 |                               | Gold                        | 7440-57-5  | 11.50000%                          |
|               |                                                 |                               | Polydimethylsiloxane rubber | 63394-02-5 | 25.00000%                          |
|               |                                                 |                               | Silicone                    | 7440-21-3  | 62.50000%                          |
| Die attach    | Sn-Pb solder                                    | 0.11000%                      | Silver                      | 7440-22-4  | 2.50000%                           |
|               |                                                 |                               | Tin                         | 7440-31-5  | 5.00000%                           |
|               |                                                 |                               | Lead                        | 7439-92-1  | 92.50000%                          |
| Encapsulation | EP (Epoxy resin)                                | 6.76000%                      | Carbon black                | 1333-86-4  | 0.30000%                           |
|               |                                                 |                               | ANTIMONY TRIOXIDE           | 1309-64-4  | 0.80000%                           |
|               |                                                 |                               | Tetrabromobisphenol A       | 79-94-7    | 0.99000%                           |
|               |                                                 |                               | Epoxy resin 89              | 26335-32-0 | 27.61000%                          |
|               |                                                 |                               | Quartz sand                 | 60676-86-0 | 70.30000%                          |
| Leadfinish    | Tin plating                                     | 0.07000%                      | Nickel                      | 8049-31-8  | 100.00000%                         |
| Leadframe     | Copper (e.g. copper amounts in cable harnesses) | 8.61000%                      | Copper                      | 7440-50-8  | 100.00000%                         |
| Plating       | Copper plating                                  | 2.53000%                      | Nickel                      | 7440-02-0  | 100.00000%                         |

**Attached parts list**

| Part number | Part name | Part Mass | Part Mass UoM |
|-------------|-----------|-----------|---------------|
| BYPxx/BYZxx | Pressfit  | 7         | g             |